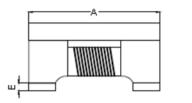


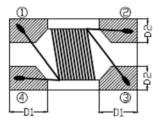
FEATRLRES

- High common mode impedance at high frequency cause excellent noise suppression performance.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)







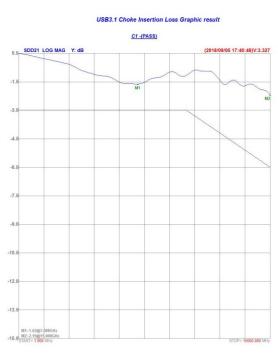
Size	А	В	С	D1	D2	E
2012F2SF	2.0±0.2	1.2±0.2	1.2±0.2	0.50 ± 0.1	0.51±0.1	0.15±0.1

ELECTRICAL CHARACTERISTICS

	Impedance (Ω)	Test	DC	Rated	Rated Volt.	Withstand	IR
Part Number		Frequency	Resistance	Current	(Vdc)max.	Volt. (Vdc)	(Ω) min.
		(MHz)	(Ω) max .	(mA)max.	(Vuc)max.	max.	(32) 11111.
HSF2012F2SF-300T04-H	30±25%	100	0.20	400	50	125	10M
HSF2012F2SF-600T03-H	60±25%	100	0.30	300	50	125	10M
HSF2012F2SF-900T03-H	90±25%	100	0.30	300	50	125	10M

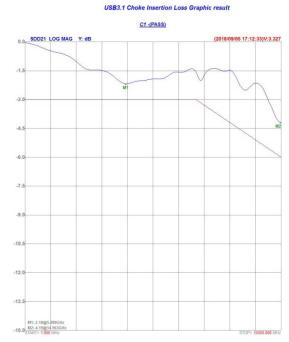


Insertion Loss Test

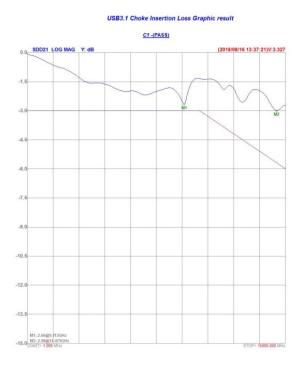


HSF2012F2SF-300

HSF2012F2SF-600

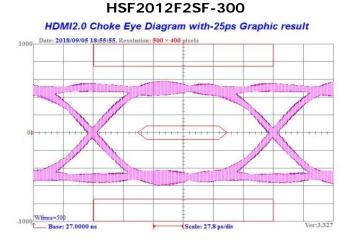


HSF2012F2SF-900

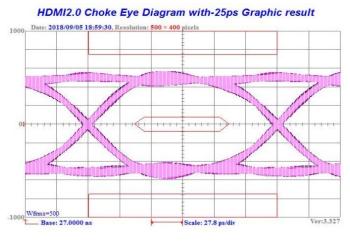




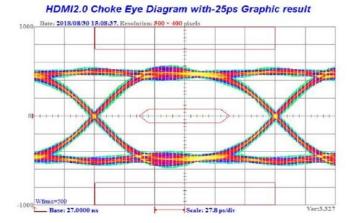
Eye Digram Graphic Test



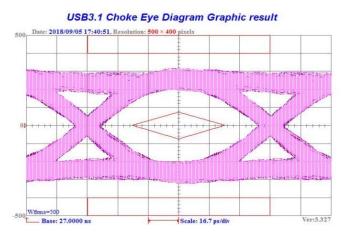
HSF2012F2SF-600



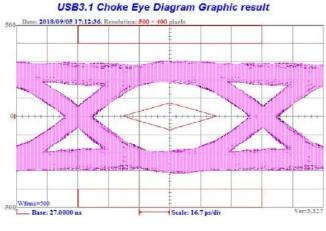
HSF2012F2SF-900



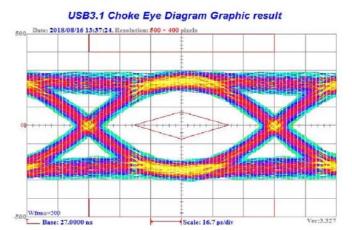
HSF2012F2SF-300



HSF2012F2SF-600



HSF2012F2SF-900





Reliability and Test Condition

Item	Performance	Test Condition					
Operating temperature	-40~+125℃ (Including self - temperature rise)						
Storage temperature	110~+40℃,50~60%RH (Product with taping) 240~+125℃ (on board)						
Electrical Performance Test	•	•					
Inductance		HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.					
DCR	 Refer to standard electrical characteristics list. 	CH16502,Agilent33420A Micro-Ohm Meter.					
Saturation Current (Isat)	Approximately∆L30%	Saturation DC Current (Isat) will cause L0 to drop \triangle L(%)					
Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer					
Reliability Test							
Life Test		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature : 125±2°C (Inductor) Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs					
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity : 85±2 * R.H, Temperature : 85°C±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs					
Moisture Resistance	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	 Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs, keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs. 					
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD- 020DClassification Reflow Profiles Condition for 1 cycle Step1 : $-40\pm2^{\circ}$ 30 \pm 5min Step2 : $25\pm2^{\circ}$ \leq 0.5min Step3 : $125\pm2^{\circ}$ 30 \pm 5min Number of cycles : 500 Measured at room temperature after placing for 24 \pm 2 hrs					
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations).					
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.					
Shock	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Type Peak value (g's) Normal duration (D) (ms) Wave form Velocity change (Vi)ft/sec SMD 50 11 Half-sine 11.3 Lead 50 11 Half-sine 11.3					
Solder ability	More than 95% of the terminal electrode should be covered with solder。	Preheat: 150°C,60sec.₀ Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ∘ Flux for lead free: Rosin. 9.5% ∘ Dip time: 4±1sec ∘					



		Depth: completely cover the termination			
		Depth: completely cover the termination			
Resistance to Soldering Heat		Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate Number of heat cycles			
		260 ±5 (solder temp) 10 ±1 25mm/s ±6 mm/s 1			
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD- 020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg, <<0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.			

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.